
Automotive Chiplet Forum – Spring 2026

2–3 June 2026 | imec, Leuven, Belgium

LTSCCT participated in the **Automotive Chiplet Forum – Spring 2026**, hosted by **imec**, reinforcing its commitment to advancing next-generation semiconductor technologies for the automotive industry and contributing to conversations shaping the future of intelligent mobility. The forum brought together industry leaders, technologists, automotive OEMs, and semiconductor experts to explore the role of chiplet-based architectures in enabling scalable, high-performance, and software-defined automotive platforms.

A key highlight of LTSCCT's participation was a keynote presentation by **Garima Jain, Product Management Lead, Compute Business Unit, LTSCCT**, who shared insights into the evolving semiconductor architectures powering the next generation of Software-Defined Vehicles (SDVs).

Highlights

Keynote Presentation

Speaker: Garima Jain, Product Management Lead, Compute BU, LTSCCT

Topic: *The Modular Mandate: Driving the SDV through UCle-Enabled Heterogeneous Architectures*

